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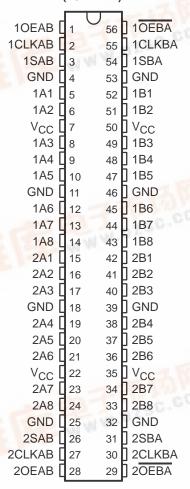
- Members of the Texas Instruments
 Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce)
 1 V at V_{CC} = 5 V, T_A = 25°C
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'ABT16652 are 16-bit bus transceivers that consist of D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. These devices can be used as two 8-bit transceivers or one 16-bit transceiver.

Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. A low input selects real-time data, and a high input selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT16652.

SN54ABT16652 . . . WD PACKAGE SN74ABT16652 . . . DL PACKAGE (TOP VIEW)



Data on the A- or B-data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the select- or enable-control inputs. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

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description (continued)

To ensure the high-impedance state during power up or power down, $\overline{\text{OEBA}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver (B to A). OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver (A to B).

The SN54ABT16652 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16652 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

			UTS			DATA	A 1/0†	ODERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	1	↑	Χ	Χ	Input	Input	Store A and B data
Х	Н	1	H or L	Х	Χ	Input	Unspecified [‡]	Store A, hold B
Н	Н	\uparrow	\uparrow	X‡	Χ	Input	Output	Store A in both registers
L	Х	H or L	↑	Х	Х	Unspecified [‡]	Input	Hold A, store B
L	L	\uparrow	\uparrow	X	X‡	Output	Input	Store B in both registers
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	X	Н	Output	Input	Stored B data to A bus
Н	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
Н	Н	H or L	Χ	Н	Χ	Input	Output	Stored A data to B bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

[†] The data-output functions may be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

Select control = H; clocks must be staggered to load both registers.



[‡] Select control = L; clocks can occur simultaneously.

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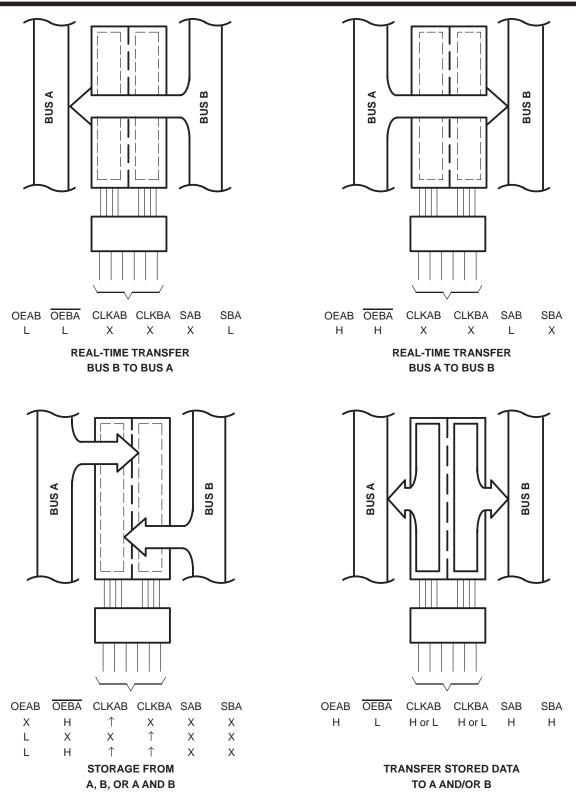
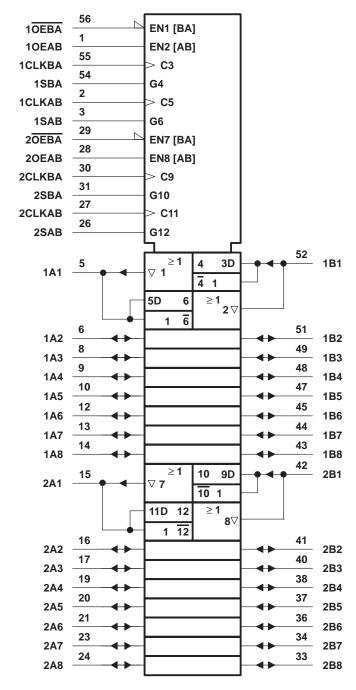


Figure 1. Bus-Management Functions



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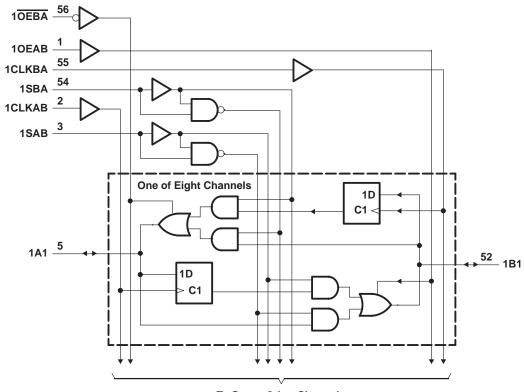
logic symbol†



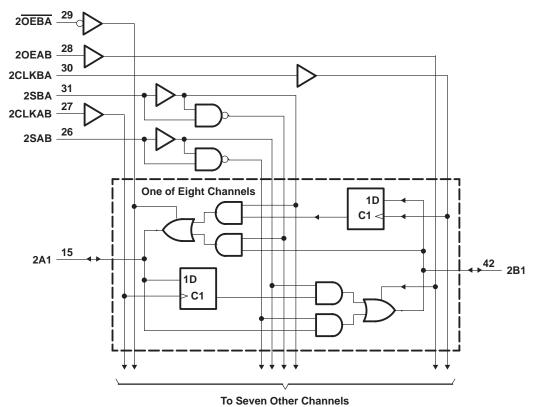
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



To Seven Other Channels



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16652	96 mA
SN74ABT16652	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	
Package thermal impedance, θ _{JA} (see Note 2): DL package	74°C/W
Storage temperature range, T _{stg}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN54AB1	16652	SN74AB1	16652	UNIT	
			MIN	MAX	MIN	MAX	UNIT	
VCC	Supply voltage		4.5	5.5	4.5	5.5	V	
VIH	High-level input voltage		2		2		V	
VIL	Low-level input voltage			0.8		0.8	V	
VI	Input voltage			VCC	0	VCC	V	
IOH	High-level output current			-24		-32	mA	
l _{OL}	Low-level output current	ow-level output current		48		64	mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V	
TA	Operating free-air temperature	_	-55	125	-40	85	°C	

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST COM	T _A = 25°C			SN54AB	Г16652	SN74AB1	UNIT			
PAR	KAWETER	TEST CON	DITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V	
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5			2.5		2.5			
VOH		V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				V	
		VCC = 4.5 V	I _{OH} = -32 mA	2*					2			
Vai		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100						mV	
I _I	Control inputs	V _{CC} = 5.5 V, V _I = V ₀	CC or GND			±1		±1		±1	μΑ	
	A or B ports					±20		±20		±20		
lozh‡		$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			10		10		10	μΑ	
lozL [‡]		$V_{CC} = 5.5 \text{ V},$	$V_0 = 0.5 V$			-10		-10		-10	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ	
I _O §		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high			2		2		2		
ICC	A or B ports	$I_0 = 0$,	Outputs low			32		32		32	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2		
	Data inputs	$V_{CC} = 5.5 \text{ V},$ One input at 3.4 V,	Outputs enabled			50		50		50		
∆ICC¶	Data Inputs	Other inputs at V _{CC} or GND	Outputs disabled			50		50		50	μΑ	
	Control inputs	$V_{CC} = 5.5 \text{ V}$, One in Other inputs at V_{CC}				50		50		50		
Ci	Control inputs	V _I = 2.5 V or 0.5 V			4						pF	
C _{io}	A or B ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			8						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



[†] All typical values are at V_{CC} = 5 V. [‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

			SN54AE	T16652		
		V _{CC} =	= 5 V, 25°C	MIN	MAX	UNIT
		MIN	MAX			
fclock	Clock frequency	0	125	0	125	MHz
t _W	Pulse duration, CLK high or low	4.3		4.3		ns
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3.5		4		ns
th	Hold time, A or B after CLKAB↑ or CLKBA↑	0.5		0.5		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		V _{CC} =	= 5 V, 25°C	MIN	MAX	UNIT
		MIN	MAX			
fclock	Clock frequency	0	125	0	125	MHz
t _W	Pulse duration, CLK high or low	4.3		4.3		ns
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3		ns
th	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		ns

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
fmax			125			125		MHz
^t PLH	CLK	B or A	1.5	3.1	4	1	5	ns
t _{PHL}	CLK	BOIA	1.5	3.2	4.1	1	5	115
t _{PLH}	A or B	B or A	1	2.3	3.2	0.6	4	ns
t _{PHL}		BUIA	1	3	4.1	0.6	4.9	110
^t PLH	SAB or SBA [†]	B or A	1	2.9	4.3	0.6	5.3	ns
t _{PHL}		BOIA	1	3.1	4.6	0.6	5.3	110
^t PZH	 OEBA	А	1	2.8	4.1	0.6	5.2	ns
t _{PZL}	OEBA		1.5	3.1	4.4	1	5.4	115
^t PHZ	<u> </u>	А	1.5	3.4	4.7	0.8	5.3	ns
^t PLZ	OEBA		1.5	2.7	4	1	5.3	
^t PZH	OFAR	В	1	2.6	3.6	0.8	4.7	20
t _{PZL}	OEAB		1.5	2.8	4.5	1	5	ns
^t PHZ	OEAB	В	2	4.2	5.9	1	6.4	
t _{PLZ}	UEAB		1.5	3.4	4.9	1	5.9	ns

[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

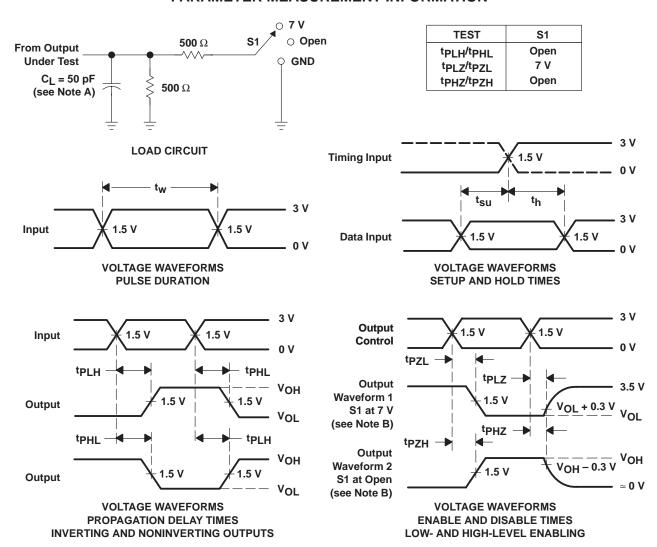
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
f _{max}			125			125		MHz
^t PLH	CLK	B or A	1.5	3.1	4	1.5	4.9	ns
t _{PHL}		BUIA	1.5	3.2	4.1	1.5	4.7	115
t _{PLH}	A or B	B or A	1	2.3	3.2	1	3.9	ns
t _{PHL}		BULK	1	3	4.1	1	4.6	115
t _{PLH}	SAB or SBA†	B or A	1	2.9	4.3	1	5	ns
t _{PHL}		BULK	1	3.1	4.3	1	5	115
^t PZH	OEBA	А	1	2.8	4.1	1	5	ns
t _{PZL}	OEBA		1.5	3.1	4.4	1.5	5.3	
t _{PHZ}	OFDA	А	1.5	3.4	4.4	1.5	4.9	ns
t _{PLZ}	OEBA	A	1.5	2.7	3.6	1.5	4	1115
^t PZH	OFAR	В	1	2.6	3.6	1	4.2	ns
t _{PZL}	OEAB		1.5	2.8	3.9	1.5	4.6	115
^t PHZ	OEAB	В	2	4.2	5.5	2	5.9	
^t PLZ	OEAB		1.5	3.4	4.5	1.5	5.2	ns

[†]These parameters are measured with the internal output state of the storage register opposite that of the bus input.



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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \ \Omega$, $t_f \leq 2.5 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms



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